

TMS 2015

144th Annual Meeting & Exhibition

March 15-19, 2015 • Walt Disney World
Orlando, Florida, USA

TMS
PROFESSIONAL
DEVELOPMENT
EVENT

Make the Most of Your Travel to Orlando: Participate in a TMS Professional Development Course

11TH ANNUAL LEAD-FREE SOLDERS AND INTERCONNECT TECHNOLOGY WORKSHOP

Sunday, March 15, 2015 • 8:30 a.m. – 4:30 p.m.

Sponsored by the TMS Functional Materials Division (formerly EMPMD)

COURSE OVERVIEW

This annual workshop provides updates on changes, practices, and the future of the industry. Through presentations and extensive discussion regarding key topics, this workshop will provide a bridge between companies, academic research groups, national laboratories, and consortia, and will lead to the materials science fundamentals necessary for further understanding and future industry applications.

A detailed workshop agenda will be available in late autumn. Please check the website for details.

WHAT ATTENDEES ARE SAYING

“The workshop provided a great overview of the past and current lead-free solder technologies as well as the status of current and future needs within the microelectronics industry. This workshop was a great opportunity for learning and discussion, and it was a fantastic way to kick off the TMS conference!”

– 2014 Workshop Attendee

REGISTRATION INFORMATION

Register for the 11th Annual Lead-Free Solders and Interconnect Technology Workshop through the TMS 2015 Annual Meeting & Exhibition registration form.

REGISTRATION FEES

Before February 9, 2015

Member \$15
Nonmember \$125
Student \$15

After February 9, 2015

Member \$25
Nonmember \$175
Student \$125

For more information on professional development courses, visit:

www.tms.org/PD2015